

RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	JUN '99	24325	9915 ATP (Anam, PI)	DK815282AAB	SOIC	50	47	0
DS1869	A3	SEP '99	24445	9907 NSEB	DJ824247ABA	SOIC	25	46	0

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 217C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C2	JUN '99	23958	9915 Carsem S	DM846764AA	SOIC	3	238	0
DS87C520	A14	NOV '99	24798	9931 ASI (Anam, K)	DN901118AAB	LCC	3	226	2
DS87C520	A14	FEB '00	25118	4 ATP (Anam, PI)	DK935356AAB	LCC	3	234	1

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232	C2-L	APR '99	23660	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	4	0
DS1232	C2-L	JAN '00	25019	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	4	0
DS1233	A5	APR '99	23662	9911	Carsem	DM837033AB	SOT223	4	0
DS1233	A5	JAN '00	25033	9952	Carsem	DM929359AB	SOT223	4	0
DS1267	A1	AUG '99	24340	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	4	0
DS1621	A7	JUN '99	24314	9915	ATP (Anam, PI)	DK815282AAB	SOIC	4	0
DS1621	A7	MAR '00	25217	9950	OSEP	DE940040AAC	SOIC	4	0
DS17485	A4-5	AUG '99	24359	9906	ATP (Anam, PI)	DK838211AAF	SOIC	4	0
DS1803	A2	NOV '98	22797	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	4	0
DS1803	A2	FEB '99	23274	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	4	0
DS1803	A2	AUG '99	24367	9909	ATP (Anam, PI)	DK830515AAB	SOIC	4	0
DS1803	A2	NOV '99	24735	9923	ATP (Anam, PI)	DK913631AAA	SOIC	4	0
DS1803	A2	MAY '00	25435	13	OSEP	DE951193AAF	SOIC	4	0
DS1869	A3	SEP '99	24438	9907	NSEB	DJ824247ABA	SOIC	4	0
DS2108	B7	FEB '00	25103	9951	ATP (Anam, PI)	DK940069AAC	SOIC	4	0
DS2109	A7	DEC '99	24805	9842	Carsem	DM812689AA	SOIC	4	0
DS2118M	B1	MAR '00	25230	5	ASI (Anam, K)	ZN946350AAG	SSOP	4	0
DS2154	A2	MAR '00	25238	7	ATP (Anam, PI)	DK948587AAA	LQFP	4	0
DS2175	D1	JAN '00	25041	1	ATP (Anam, PI)	DK941179AAD	SOIC	4	0
DS21S07	C1-	NOV '99	24727	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	4	0
DS21S07	C1-	FEB '00	25095	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	4	0
DS21S07	C1-	MAY '00	25443	13	Carsem S	DM002285AAF	TSSOP	4	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS2502	C2	JUN '99	23957	9915 Carsem S	DM846764AA	SOIC	4 0
DS2502	C2	SEP '99	24477	9918 Carsem S	DM849359AC	SOIC	4 0
DS2502	C3	MAR '00	25250	5 Carsem S	DM941226AA	SOIC	4 0
DS87C520	A14	NOV '99	24797	9931 ASI (Anam, K)	DN901118AAB	LCC	4 0
DS87C520	A14	FEB '00	25117	4 ATP (Anam, PI)	DK935356AAB	LCC	4 0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2250	E-T	MAR '00	25290	12	Dallas	116859	SipStick w/Confor	100	11	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY			LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY	POINT			QTY	FAIL	
DS1000	E3	OCT '99	24793	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	300	40	0	
DS1000	E3	OCT '99	24793	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	1000	40	0	
DS1000	E3	JAN '00	25002	2	CPS (ChipPac, China)	DH938700AB	PDIP	300	40	0	
DS1000	E3	JAN '00	25002	2	CPS (ChipPac, China)	DH938700AB	PDIP	1000	40	0	
DS1000	E3	APR '00	25408	9	CPS (ChipPac, China)	DH949661AEA	PDIP	300	40	0	
DS1232	C2-L	APR '99	24191	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	300	40	0	
DS1232	C2-L	APR '99	24191	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	1000	40	0	
DS1233	A5	APR '99	23940	9911	Carsem	DM837033AB	SOT223	300	40	0	
DS1233	A5	APR '99	23940	9911	Carsem	DM837033AB	SOT223	1000	40	0	
DS1267	A1	AUG '99	24345	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	300	40	0	
DS1267	A1	AUG '99	24345	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	1000	40	0	
DS1302	A3	MAR '00	25213	6	CPS (ChipPac, China)	DH945115AAB	PDIP	300	40	0	
DS1302	A3	MAR '00	25213	6	CPS (ChipPac, China)	DH945115AAB	PDIP	1000	40	0	
DS1621	A7	JUN '99	24323	9915	ATP (Anam, PI)	DK815282AAB	SOIC	300	40	0	
DS1621	A7	JUN '99	24323	9915	ATP (Anam, PI)	DK815282AAB	SOIC	1000	40	0	
DS17485	A4-5	AUG '99	24364	9906	ATP (Anam, PI)	DK838211AAF	SOIC	300	50	0	
DS17485	A4-5	AUG '99	24364	9906	ATP (Anam, PI)	DK838211AAF	SOIC	1000	50	0	
DS1803	A2	NOV '98	23924	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	300	40	0	
DS1803	A2	NOV '98	23924	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	1000	40	0	
DS1803	A2	FEB '99	24004	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	300	40	0	
DS1803	A2	FEB '99	24004	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	1000	40	0	
DS1803	A2	AUG '99	24372	9909	ATP (Anam, PI)	DK830515AAB	SOIC	300	40	0	

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1803	A2	AUG '99	24372	9909	ATP (Anam, PI)	DK830515AAB	SOIC	1000	40	0
DS1803	A2	NOV '99	24740	9923	ATP (Anam, PI)	DK913631AAA	SOIC	300	40	0
DS1803	A2	NOV '99	24740	9923	ATP (Anam, PI)	DK913631AAA	SOIC	1000	40	2
DS1869	A3	SEP '99	24443	9907	NSEB	DJ824247ABA	SOIC	300	38	0
DS1869	A3	SEP '99	24443	9907	NSEB	DJ824247ABA	SOIC	1000	38	0
DS2108	B7	FEB '00	25108	9951	ATP (Anam, PI)	DK940069AAC	SOIC	300	40	0
DS2108	B7	FEB '00	25108	9951	ATP (Anam, PI)	DK940069AAC	SOIC	1200	40	0
DS2118M	B1	MAR '00	25235	5	ASI (Anam, K)	ZN946350AAG	SSOP	300	35	0
DS2154	A2	MAR '00	25243	7	ATP (Anam, PI)	DK948587AAA	LQFP	300	66	0
DS2175	D1	JAN '00	25046	1	ATP (Anam, PI)	DK941179AAD	SOIC	300	40	0
DS2175	D1	JAN '00	25046	1	ATP (Anam, PI)	DK941179AAD	SOIC	1100	40	0
DS21S07	C1-	NOV '99	24732	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	300	40	0
DS21S07	C1-	NOV '99	24732	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	1000	40	0
DS21S07	C1-	FEB '00	25100	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	300	38	0
DS2401	C2	MAR '00	25247	7	Fastech	DA925802AJA	TO92	300	40	0
DS2401	C2	MAR '00	25247	7	Fastech	DA925802AJA	TO92	1000	40	0
DS2434	D1	FEB '00	25113	1	Carsem	DM831669AA	TO226 (PR35)	300	50	0
DS2434	D1	FEB '00	25113	1	Carsem	DM831669AA	TO226 (PR35)	1000	50	0
DS2502	C2	JUN '99	24175	9915	Carsem S	DM846764AA	SOIC	300	40	0
DS2502	C2	JUN '99	24175	9915	Carsem S	DM846764AA	SOIC	1000	40	0
DS2502	C2	SEP '99	24482	9918	Carsem S	DM849359AC	SOIC	300	43	0
DS2502	C2	SEP '99	24482	9918	Carsem S	DM849359AC	SOIC	1000	43	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C3	JAN '00	25052	9930 CPS (ChipPac, China)	DH917304BAA	TSOC	300	77	0
DS2502	C3	JAN '00	25052	9930 CPS (ChipPac, China)	DH917304BAA	TSOC	1000	77	0
DS80C320	C5	OCT '99	24586	9938 CPS (ChipPac, China)	DH925592AAB	PDIP	300	40	0
DS80C320	C5	OCT '99	24586	9938 CPS (ChipPac, China)	DH925592AAB	PDIP	1000	40	0
DS80C320	C5	JAN '00	25016	1 CPS (ChipPac, China)	DH928322BAA	PDIP	300	40	0
DS87C520	A14	NOV '99	24802	9931 ASI (Anam, K)	DN901118AAB	LCC	300	40	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-Y	OCT '99	24561	9939	Dallas	109958	Low Profile Module	300	77	0
DS1230	B1-Y	OCT '99	24561	9939	Dallas	109958	Low Profile Module	1000	77	0
DS1230	B1-Y	JAN '00	25012	9944	Dallas	110596	Low Profile Module	300	77	0
DS1230	B1-	JAN '00	25008	9952	Fastech	114146	Module w/SMT	300	100	0
DS12887	A2	JAN '00	25031	9950	Fastech	115426	Module w/Bent Fra	300	100	0
DS1386	A1	FEB '00	25267	10	Fastech	115652	Power Cap	300	77	0
DS1386	A1	FEB '00	25267	10	Fastech	115652	Power Cap	1000	77	0
DS1643	C1	AUG '99	24351	9929	Dallas	111344	Module w/Hi Densit	300	77	0
DS1643	C1	AUG '99	24351	9929	Dallas	111344	Module w/Hi Densit	1000	77	3
DS1643	C1	NOV '99	24725	9939	Dallas	113476	Module w/Hi Densit	300	77	0
DS1643	C1	NOV '99	24725	9939	Dallas	113476	Module w/Hi Densit	1000	77	0
DS1643	C1	FEB '00	25093	4	Dallas	116705	Module w/Hi Densit	300	77	0
DS1991	E8	MAR '00	25228	9	Dallas	DS851044AA-	T5 w/welded Tabs	300	77	0
DS1991	E8	MAR '00	25228	9	Dallas	DS851044AA-	T5 w/welded Tabs	1000	77	0
DS5000	D6-T	FEB '00	25199	6	Dallas	115605	SBDIP	300	15	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1621	A7	JUN '99	24326	9915	ATP (Anam, PI)	DK815282AAB	SOIC	336	45	1
DS1621	A7	JUN '99	24326	9915	ATP (Anam, PI)	DK815282AAB	SOIC	1000	45	0
DS1869	A3	SEP '99	24446	9907	NSEB	DJ824247ABA	SOIC	336	46	0
DS1869	A3	SEP '99	24446	9907	NSEB	DJ824247ABA	SOIC	1000	46	0
DS2502	C2	JUN '99	24177	9915	Carsem S	DM846764AA	SOIC	336	37	0
DS2502	C2	JUN '99	24177	9915	Carsem S	DM846764AA	SOIC	1000	37	0
DS2502	C2	SEP '99	24484	9918	Carsem S	DM849359AC	SOIC	336	34	0
DS2502	C2	SEP '99	24484	9918	Carsem S	DM849359AC	SOIC	1000	34	0
DS87C520	A14	NOV '99	24804	9931	ASI (Anam, K)	DN901118AAB	LCC	336	43	0
DS87C520	A14	NOV '99	24804	9931	ASI (Anam, K)	DN901118AAB	LCC	1000	43	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	B1-Y	OCT '99	24560	9939	Dallas	109958	Low Profile Module	336	77	0
DS1230	B1-Y	OCT '99	24560	9939	Dallas	109958	Low Profile Module	1000	77	0
DS1230	B1-Y	JAN '00	25011	9944	Dallas	110596	Low Profile Module	336	77	0
DS1230	B1-Y	JAN '00	25011	9944	Dallas	110596	Low Profile Module	1000	77	0
DS1386	A1	FEB '00	25266	10	Fastech	115652	Power Cap	336	77	0
DS1643	C1	AUG '99	24350	9929	Dallas	111344	Module w/Hi Densit	336	77	0
DS1643	C1	AUG '99	24350	9929	Dallas	111344	Module w/Hi Densit	1000	77	0
DS1643	C1	NOV '99	24724	9939	Dallas	113476	Module w/Hi Densit	336	77	0
DS1643	C1	NOV '99	24724	9939	Dallas	113476	Module w/Hi Densit	1000	77	0
DS1643	C1	FEB '00	25092	4	Dallas	116705	Module w/Hi Densit	336	77	0
DS1643	C1	FEB '00	25092	4	Dallas	116705	Module w/Hi Densit	1000	77	0
DS1991	E8	MAR '00	25227	9	Dallas	DS851044AA-	T5 w/welded Tabs	336	77	0
DS1991	E8	MAR '00	25227	9	Dallas	DS851044AA-	T5 w/welded Tabs	1000	77	1
DS5000	D6-T	FEB '00	25198	6	Dallas	115605	SBDIP	336	15	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-	JAN '00	25007	9952 Fastech	114146	Module w/SMT	48	200	0
DS1230	B1-Y	APR '00	25414	5 Fastech	118511	Module w/SMT	48	200	0
DS2250	E-T	MAR '00	25289	12 Dallas	116859	SipStick w/Confor	336	11	0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1230	B1-	JAN '00	25005	9952 Fastech	114146	Module w/SMT	3 0
DS1230	B1-Y	APR '00	25412	5 Fastech	118511	Module w/SMT	3 0
DS12887	A2	JAN '00	25028	9950 Fastech	115426	Module w/Bent Fra	3 0
DS1643	C1	AUG '99	24348	9929 Dallas	111344	Module w/Hi Densit	3 0
DS1643	C1	NOV '99	24722	9939 Dallas	113476	Module w/Hi Densit	3 0
DS1643	C1	FEB '00	25090	4 Dallas	116705	Module w/Hi Densit	3 0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: SOLDERABILITY, 4 HR STEAM AGE, 245C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5000	D6-T	MAY '00	25530	20	Dallas	117838	SBDIP		3	0

RELIABILITY MONITOR

STRESS: SOLDER HEAT

CONDITIONS: HTC VAPOR PHASE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1803	A2	NOV '98	22798	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	3	238	0
DS1803	A2	FEB '99	23275	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	3	238	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO		CODE	FACILITY			POINT	QTY
DS1232	C2-L	APR '99	24188	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC		4	0
DS1232	C2-L	JAN '00	25021	9948	ATP (Anam, PI)	DK933191AAJ	SOIC		4	0
DS1233	A5	APR '99	23772	9911	Carsem	DM837033AB	SOT223		4	0
DS1233	A5	JAN '00	25035	9952	Carsem	DM929359AB	SOT223		4	0
DS1267	A1	AUG '99	24342	9823	ATP (Anam, PI)	DK807766AAE	TSSOP		4	0
DS1621	A7	JUN '99	24316	9915	ATP (Anam, PI)	DK815282AAB	SOIC		4	0
DS17485	A4-5	AUG '99	24361	9906	ATP (Anam, PI)	DK838211AAF	SOIC		4	0
DS1803	A2	NOV '98	23172	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC		4	0
DS1803	A2	FEB '99	23927	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC		4	0
DS1803	A2	AUG '99	24369	9909	ATP (Anam, PI)	DK830515AAB	SOIC		4	0
DS1803	A2	NOV '99	24737	9923	ATP (Anam, PI)	DK913631AAA	SOIC		4	0
DS1869	A3	SEP '99	24440	9907	NSEB	DJ824247ABA	SOIC		4	0
DS2108	B7	FEB '00	25105	9951	ATP (Anam, PI)	DK940069AAC	SOIC		4	0
DS2109	A7	DEC '99	24807	9842	Carsem	DM812689AA	SOIC		4	1
DS2118M	B1	MAR '00	25232	5	ASI (Anam, K)	ZN946350AAG	SSOP		4	0
DS2154	A2	MAR '00	25240	7	ATP (Anam, PI)	DK948587AAA	LQFP		4	0
DS2175	D1	JAN '00	25043	1	ATP (Anam, PI)	DK941179AAD	SOIC		4	0
DS21S07	C1-	NOV '99	24729	9908	ATP (Anam, PI)	DK836680AAF	TSSOP		4	0
DS21S07	C1-	FEB '00	25097	9937	ATP (Anam, PI)	DK926747AAP	TSSOP		4	0
DS2502	C2	JUN '99	24168	9915	Carsem S	DM846764AA	SOIC		4	0
DS2502	C2	SEP '99	24479	9918	Carsem S	DM849359AC	SOIC		4	0
DS2502	C3	JAN '00	25051	9930	CPS (ChipPac, China)	DH917304BAA	TSOC		4	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS2502	C3	MAR '00	25252	5 Carsem S	DM941226AA	SOIC	4 0
DS87C520	A14	NOV '99	24799	9931 ASI (Anam, K)	DN901118AAB	LCC	4 0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1230	B1-Y	OCT '99	24559	9939 Dallas	109958	Low Profile Module	6 0
DS1230	B1-Y	JAN '00	25010	9944 Dallas	110596	Low Profile Module	6 0
DS1230	B1-	JAN '00	25006	9952 Fastech	114146	Module w/SMT	6 0
DS1230	B1-Y	APR '00	25413	5 Fastech	118511	Module w/SMT	6 0
DS12887	A2	JAN '00	25029	9950 Fastech	115426	Module w/Bent Fra	6 0
DS1643	C1	AUG '99	24349	9929 Dallas	111344	Module w/Hi Densit	6 0
DS1643	C1	NOV '99	24723	9939 Dallas	113476	Module w/Hi Densit	6 0
DS1643	C1	FEB '00	25091	4 Dallas	116705	Module w/Hi Densit	6 0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: PHYSICAL DIMENSIONS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5000	D6-T	MAY '00	25531	20	Dallas	117838	SBDIP		2	0

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	B1-Y	OCT '99	24562	9939	Dallas	109958	Low Profile Module	288	77	0
DS1230	B1-Y	OCT '99	24562	9939	Dallas	109958	Low Profile Module	960	77	0
DS1230	B1-Y	JAN '00	25013	9944	Dallas	110596	Low Profile Module	288	77	0
DS1230	B1-Y	JAN '00	25013	9944	Dallas	110596	Low Profile Module	960	77	0
DS1230	B1-	JAN '00	25009	9952	Fastech	114146	Module w/SMT	288	100	0
DS1386	A1	FEB '00	25268	10	Fastech	115652	Power Cap	288	77	1
DS1643	C1	AUG '99	24352	9929	Dallas	111344	Module w/Hi Densit	288	77	0
DS1643	C1	AUG '99	24352	9929	Dallas	111344	Module w/Hi Densit	960	77	1
DS1643	C1	NOV '99	24726	9939	Dallas	113476	Module w/Hi Densit	288	77	0
DS1643	C1	NOV '99	24726	9939	Dallas	113476	Module w/Hi Densit	960	77	0
DS1643	C1	FEB '00	25094	4	Dallas	116705	Module w/Hi Densit	288	77	0
DS1643	C1	FEB '00	25094	4	Dallas	116705	Module w/Hi Densit	960	77	0
DS1991	E8	MAR '00	25229	9	Dallas	DS851044AA-	T5 w/welded Tabs	288	77	0
DS1991	E8	MAR '00	25229	9	Dallas	DS851044AA-	T5 w/welded Tabs	960	77	0
DS2250	E-T	MAR '00	25291	12	Dallas	116859	SipStick w/Confor	192	11	0
DS5000	D6-T	FEB '00	25200	6	Dallas	115605	SBDIP	288	15	0

RELIABILITY MONITOR

STRESS: INFANT LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2	JAN '00	25030	9950	Fastech	115426	Module w/Bent Fra	48	200	0

RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2154	A2	MAR '00	25244	7	ATP (Anam, PI)	DK948587AAA	LQFP	200	77	0

RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	APR '99	24192	9848 CPK (ChipPac, Korea)	DL829603AAC	SOIC	100	77	0
DS1233	A5	APR '99	23941	9911 Carsem	DM837033AB	SOT223	100	72	0
DS1233	A5	JAN '00	25039	9952 Carsem	DM929359AB	SOT223	100	72	0
DS2401	C2	MAR '00	25248	7 Fastech	DA925802AJA	TO92	100	77	0
DS2434	D1	FEB '00	25114	1 Carsem	DM831669AA	TO226 (PR35)	100	70	0
DS87C520	A14	NOV '99	24803	9931 ASI (Anam, K)	DN901118AAB	LCC	100	56	0

RELIABILITY MONITOR

STRESS: EXTERNAL VISUAL

CONDITIONS: MIL-STD-883-2009

PRODUCT	REV	MONITOR	DATE	JOB NO	DATE ASSEMBLY	CODE	FACILITY	LOT NO.	PACKAGE	READ	POINT	QTY	FAIL
DS1233	A5		APR '99	23662	9911		Carsem	DM837033AB	SOT223			4	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					CODE	FACILITY	POINT
DS1232	C2-L	APR '99	23661	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	3	238	0
DS1232	C2-L	JAN '00	25020	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	3	238	0
DS1233	A5	APR '99	23663	9911	Carsem	DM837033AB	SOT223	3	233	0
DS1233	A5	JAN '00	25034	9952	Carsem	DM929359AB	SOT223	3	233	0
DS1267	A1	AUG '99	24341	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	3	238	0
DS1621	A7	JUN '99	24315	9915	ATP (Anam, PI)	DK815282AAB	SOIC	3	241	0
DS1621	A7	MAR '00	25218	9950	OSEP	DE940040AAC	SOIC	3	241	0
DS17485	A4-5	AUG '99	24360	9906	ATP (Anam, PI)	DK838211AAF	SOIC	3	237	0
DS1803	A2	AUG '99	24368	9909	ATP (Anam, PI)	DK830515AAB	SOIC	3	238	0
DS1803	A2	NOV '99	24736	9923	ATP (Anam, PI)	DK913631AAA	SOIC	3	238	0
DS1869	A3	SEP '99	24439	9907	NSEB	DJ824247ABA	SOIC	3	241	0
DS2108	B7	FEB '00	25104	9951	ATP (Anam, PI)	DK940069AAC	SOIC	3	238	0
DS2109	A7	DEC '99	24806	9842	Carsem	DM812689AA	SOIC	3	237	0
DS2118M	B1	MAR '00	25231	5	ASI (Anam, K)	ZN946350AAG	SSOP	3	238	0
DS2154	A2	MAR '00	25239	7	ATP (Anam, PI)	DK948587AAA	LQFP	3	238	0
DS2175	D1	JAN '00	25042	1	ATP (Anam, PI)	DK941179AAD	SOIC	3	238	0
DS21Q43	A3-A	JUN '00	25502	14	ASI (Anam, K)	DN004571AAB	LQFP	3	239	0
DS21S07	C1-	NOV '99	24728	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	3	238	0
DS21S07	C1-	FEB '00	25096	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	3	238	0
DS21S07	C1-	MAY '00	25444	13	Carsem S	DM002285AAF	TSSOP	3	238	0
DS2502	C2	SEP '99	24478	9918	Carsem S	DM849359AC	SOIC	3	238	0
DS2502	C3	JAN '00	25050	9930	CPS (ChipPac, China)	DH917304BAA	TSOC	3	151	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C3	MAR '00	25251	5	Carsem S	DM941226AA	SOIC	3	238	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1000	E3	OCT '99	24794	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	274	77	0
DS1000	E3	OCT '99	24794	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	959	77	0
DS1000	E3	JAN '00	25003	2	CPS (ChipPac, China)	DH938700AB	PDIP	274	77	0
DS1000	E3	JAN '00	25003	2	CPS (ChipPac, China)	DH938700AB	PDIP	959	77	0
DS1000	E3	APR '00	25409	9	CPS (ChipPac, China)	DH949661AEA	PDIP	274	77	0
DS1267	A1	AUG '99	24346	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	274	77	0
DS1267	A1	AUG '99	24346	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	959	77	0
DS12887	A2	JAN '00	25032	9950	Fastech	115426	Module w/Bent Fra	274	100	0
DS12887	A2	JAN '00	25032	9950	Fastech	115426	Module w/Bent Fra	959	100	0
DS1302	A3	MAR '00	25214	6	CPS (ChipPac, China)	DH945115AAB	PDIP	274	77	0
DS1621	A7	JUN '99	24324	9915	ATP (Anam, PI)	DK815282AAB	SOIC	274	70	0
DS1621	A7	JUN '99	24324	9915	ATP (Anam, PI)	DK815282AAB	SOIC	959	70	0
DS1803	A2	NOV '98	23925	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	274	77	0
DS1803	A2	NOV '98	23925	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	959	77	0
DS1803	A2	FEB '99	24005	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	274	77	0
DS1803	A2	FEB '99	24005	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	959	77	0
DS1803	A2	AUG '99	24373	9909	ATP (Anam, PI)	DK830515AAB	SOIC	274	77	0
DS1803	A2	AUG '99	24373	9909	ATP (Anam, PI)	DK830515AAB	SOIC	959	77	0
DS1803	A2	NOV '99	24741	9923	ATP (Anam, PI)	DK913631AAA	SOIC	274	67	0
DS1803	A2	NOV '99	24741	9923	ATP (Anam, PI)	DK913631AAA	SOIC	959	67	0
DS1869	A3	SEP '99	24444	9907	NSEB	DJ824247ABA	SOIC	274	54	0
DS1869	A3	SEP '99	24444	9907	NSEB	DJ824247ABA	SOIC	959	54	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2108	B7	FEB '00	25109	9951	ATP (Anam, PI)	DK940069AAC	SOIC	274	77	0
DS2108	B7	FEB '00	25109	9951	ATP (Anam, PI)	DK940069AAC	SOIC	959	77	0
DS2175	D1	JAN '00	25047	1	ATP (Anam, PI)	DK941179AAD	SOIC	274	77	0
DS2175	D1	JAN '00	25047	1	ATP (Anam, PI)	DK941179AAD	SOIC	959	77	0
DS21S07	C1-	NOV '99	24733	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	274	74	0
DS21S07	C1-	NOV '99	24733	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	959	74	0
DS21S07	C1-	FEB '00	25101	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	274	76	0
DS2502	C2	JUN '99	24176	9915	Carsem S	DM846764AA	SOIC	274	75	0
DS2502	C2	JUN '99	24176	9915	Carsem S	DM846764AA	SOIC	959	75	0
DS2502	C2	SEP '99	24483	9918	Carsem S	DM849359AC	SOIC	274	77	0
DS2502	C2	SEP '99	24483	9918	Carsem S	DM849359AC	SOIC	959	77	0
DS80C320	C5	OCT '99	24587	9938	CPS (ChipPac, China)	DH925592AAB	PDIP	274	77	0
DS80C320	C5	OCT '99	24587	9938	CPS (ChipPac, China)	DH925592AAB	PDIP	959	77	0
DS80C320	C5	JAN '00	25017	1	CPS (ChipPac, China)	DH928322BAA	PDIP	274	77	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C STEAM, UNBIASED

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1000	E3	OCT '99	24795	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	96	37	0
DS1000	E3	JAN '00	25004	2	CPS (ChipPac, China)	DH938700AB	PDIP	96	40	0
DS1000	E3	APR '00	25410	9	CPS (ChipPac, China)	DH949661AEA	PDIP	96	40	0
DS1232	C2-L	APR '99	24193	9848	CPK (ChipPac, Korea)	DL829603AAC	SOIC	96	36	0
DS1233	A5	APR '99	23942	9911	Carsem	DM837033AB	SOT223	96	40	0
DS1233	A5	JAN '00	25040	9952	Carsem	DM929359AB	SOT223	96	40	0
DS1267	A1	AUG '99	24347	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	96	34	0
DS1803	A2	NOV '98	23926	9833	CPK (ChipPac, Korea)	DL820412AAB	SOIC	96	40	0
DS1803	A2	FEB '99	24006	9835	CPK (ChipPac, Korea)	DL818111AAB	SOIC	96	38	1
DS1803	A2	AUG '99	24374	9909	ATP (Anam, PI)	DK830515AAB	SOIC	96	38	0
DS1803	A2	NOV '99	24742	9923	ATP (Anam, PI)	DK913631AAA	SOIC	96	40	0
DS2108	B7	FEB '00	25110	9951	ATP (Anam, PI)	DK940069AAC	SOIC	96	35	0
DS2109	A7	DEC '99	24812	9842	Carsem	DM812689AA	SOIC	96	38	0
DS2118M	B1	MAR '00	25237	5	ASI (Anam, K)	ZN946350AAG	SSOP	96	32	0
DS2175	D1	JAN '00	25048	1	ATP (Anam, PI)	DK941179AAD	SOIC	96	40	0
DS21S07	C1-	NOV '99	24734	9908	ATP (Anam, PI)	DK836680AAF	TSSOP	96	40	0
DS21S07	C1-	FEB '00	25102	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	96	38	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1302	A3	MAR '00	25215	6	CPS (ChipPac, China)	DH945115AAB	PDIP	96	39	0
DS2401	C2	MAR '00	25249	7	Fastech	DA925802AJA	TO92	96	40	0
DS2434	D1	FEB '00	25115	1	Carsem	DM831669AA	TO226 (PR35)	96	39	0
DS2502	C3	JAN '00	25053	9930	CPS (ChipPac, China)	DH917304BAA	TSOC	96	66	0
DS80C320	C5	OCT '99	24588	9938	CPS (ChipPac, China)	DH925592AAB	PDIP	96	40	1
DS80C320	C5	JAN '00	25018	1	CPS (ChipPac, China)	DH928322BAA	PDIP	96	40	0

RELIABILITY MONITOR

STRESS: 0 HR TEST

CONDITIONS: Connect Cap & Base

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1386	A1	FEB '00	25265	10 Fastech	115652	Power Cap	2	231	0